PCN Number:		20230210000.1			PCN	Date:	March 07, 2023	
Title: Qualification of TI CDAT as Additional Assembly Site for Select QFN Package Device								
Custome	PCN Manager Dept:			Quality Services				
Proposed 1st Ship Date:June 08, 2023Sample requests accepted until:Apr 08, 2023*						- 08, 2023*		
*Sample requests received after (Apr 08, 2023) will not be supported.								
Change 1	Change Type:							
Assembly Site				Design			Wafer Bump Site	
Assembly Process				Data Sheet			Wafer Bump Material	
Assembly Materials			Part number change			Wafer Bump Process		
Mechanical Specification				Test Site			Wafer Fab Site	
Packing/Shipping/Labeling				Test Process			Wafer Fab Materials	
							Wafer	Fab Process
PCN Details								

Description of Change:

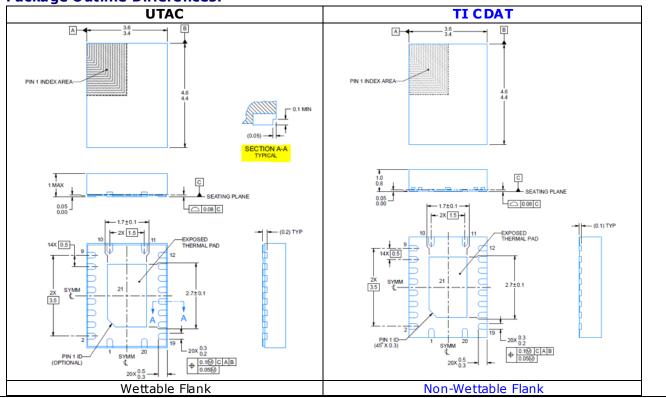
Texas Instruments Incorporated is announcing the qualification TI CDAT as Additional Assembly Site for select device listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
UTAC	NSE	THA	Bangkok
TI CDAT	CDA	CHN	Chengdu

Material Differences:

	UTAC	TI CDAT
Mount Compound	PZ0035	4207123
Wire Type	1 mil Cu	0.8mil Cu
Lead finish	Matte Sn	NiPdAu

Package Outline Differences:



Reason for Change:									
Continuity of supply.									
1) To align with world technology trends and use wiring with enhanced mechanical and									
electrical properties									
 Maximize flexibility within our Assembly/Test production sites. 									
3) Cu is easier to obtain	3) Cu is easier to obtain and stock								
Anticipated impact on I	Form, Fit, Function, Q	uality or Reliabi	lity (posi	tive / negative):					
None									
Impact on Environment	tal Ratings:								
change. If below boxes a ratings.	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.								
RoHS	REACH	Green Statu		IEC 62474					
No Change	🛛 No Change	🛛 🛛 No Change		No Change					
Changes to product ide	Changes to product identification resulting from this PCN:								
Assembly Site									
UTAC		e Origin (22L)	ASO: NSE						
TI-CDAT	Assembly Sit	e Origin (22L)	F	ASO: CDA					
Sample product shipping	label (not actual produ	ict label)							
TEXAS INSTRUMENTS 2DC:G4 2GMADE IN: Malaysia 2DC:G4 2G:MSL '2 /260C/1 YEAR SEAL DT 03/29/04G4 G4 G71:OPT: ITEM: LBL: 5A (L)T0:1750G4 									
Product Affected:	Product Affected:								
LM25145RGYR	LM25145RGYT	LM5146RGYR							

Qualification Report

Approve Date 04-Mar-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>LM5146RGYR</u> <u>and</u> LM5145RGYR	QBS Reference: <u>UCC27282</u> QDRCRQ1	QBS Reference: <u>LM74810</u> Q <u>DRRR</u> Q <u>1</u>	QBS Reference: <u>TS3A5017</u> QRGYRQ1
HAST	A2	Biased HAST	130C	96 Hours	QBS	3/231/0	3/231/0	3/231/0
UHAST	A3	Autodave	121C/15psig	96 Hours	QBS	-	3/231/0	3/231/0

UHAST	A3	Unbiased HAST	130C	96 Hou <i>r</i> s	QBS	3/231/0	-	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycl es	QBS	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hou <i>r</i> s	QBS	3/135/0	3/135/0	3/135/0

QBS: Qual By Similarity

Qual Device LM5146RGYR and LM5145RGYR are qualified at MSL2 260C

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail			
WW PCN Team	PCN ww admin team@list.ti.com			

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